



Welcome to E-XFL.COM

What is "[Embedded - Microcontrollers](#)"?

"[Embedded - Microcontrollers](#)" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "[Embedded - Microcontrollers](#)"

Details

Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	20MHz
Connectivity	-
Peripherals	Brown-out Detect/Reset, POR, WDT
Number of I/O	13
Program Memory Size	3.5KB (2K x 14)
Program Memory Type	OTP
EEPROM Size	-
RAM Size	128 x 8
Voltage - Supply (Vcc/Vdd)	4V ~ 5.5V
Data Converters	A/D 4x8b
Oscillator Type	External
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Through Hole
Package / Case	18-DIP (0.300", 7.62mm)
Supplier Device Package	18-PDIP
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic16c715-20i-p

2.0 PIC16C71X DEVICE VARIETIES

A variety of frequency ranges and packaging options are available. Depending on application and production requirements, the proper device option can be selected using the information in the PIC16C71X Product Identification System section at the end of this data sheet. When placing orders, please use that page of the data sheet to specify the correct part number.

For the PIC16C71X family, there are two device "types" as indicated in the device number:

1. **C**, as in PIC16**C**71. These devices have EPROM type memory and operate over the standard voltage range.
2. **LC**, as in PIC16**LC**71. These devices have EPROM type memory and operate over an extended voltage range.

2.1 UV Erasable Devices

The UV erasable version, offered in Cerdip package is optimal for prototype development and pilot programs. This version can be erased and reprogrammed to any of the oscillator modes.

Microchip's PICSTART® Plus and PRO MATE® II programmers both support programming of the PIC16C71X.

2.2 One-Time-Programmable (OTP) Devices

The availability of OTP devices is especially useful for customers who need the flexibility for frequent code updates and small volume applications.

The OTP devices, packaged in plastic packages, permit the user to program them once. In addition to the program memory, the configuration bits must also be programmed.

2.3 Quick-Turnaround-Production (QTP) Devices

Microchip offers a QTP Programming Service for factory production orders. This service is made available for users who choose not to program a medium to high quantity of units and whose code patterns have stabilized. The devices are identical to the OTP devices but with all EPROM locations and configuration options already programmed by the factory. Certain code and prototype verification procedures apply before production shipments are available. Please contact your local Microchip Technology sales office for more details.

2.4 Serialized Quick-Turnaround Production (SQTPSM) Devices

Microchip offers a unique programming service where a few user-defined locations in each device are programmed with different serial numbers. The serial numbers may be random, pseudo-random, or sequential.

Serial programming allows each device to have a unique number which can serve as an entry-code, password, or ID number.

PIC16C71X

4.2 Data Memory Organization

The data memory is partitioned into two Banks which contain the General Purpose Registers and the Special Function Registers. Bit RP0 is the bank select bit.

RP0 (STATUS<5>) = 1 → Bank 1

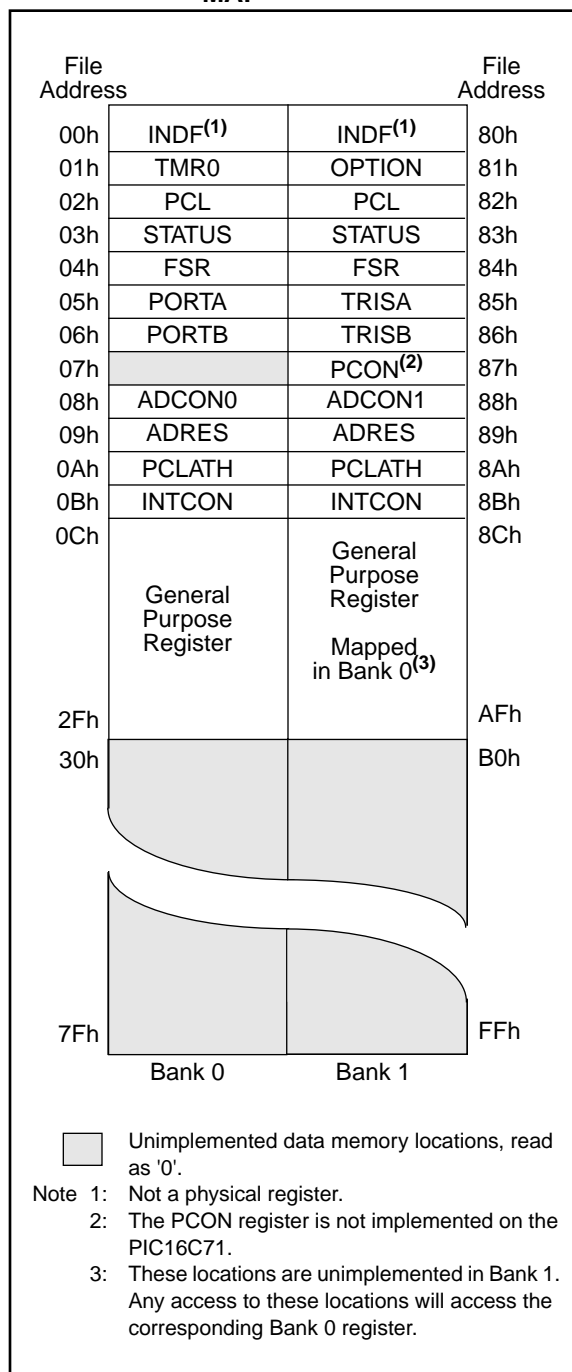
RP0 (STATUS<5>) = 0 → Bank 0

Each Bank extends up to 7Fh (128 bytes). The lower locations of each Bank are reserved for the Special Function Registers. Above the Special Function Registers are General Purpose Registers implemented as static RAM. Both Bank 0 and Bank 1 contain special function registers. Some "high use" special function registers from Bank 0 are mirrored in Bank 1 for code reduction and quicker access.

4.2.1 GENERAL PURPOSE REGISTER FILE

The register file can be accessed either directly, or indirectly through the File Select Register FSR (Section 4.5).

FIGURE 4-4: PIC16C710/71 REGISTER FILE MAP



PIC16C71X

Example 4-1 shows the calling of a subroutine in page 1 of the program memory. This example assumes that PCLATH is saved and restored by the interrupt service routine (if interrupts are used).

EXAMPLE 4-1: CALL OF A SUBROUTINE IN PAGE 1 FROM PAGE 0

```

ORG 0x500
BSF    PCLATH,3    ;Select page 1 (800h-FFFh)
BCF    PCLATH,4    ;Only on >4K devices
CALL   SUB1_P1     ;Call subroutine in
:         ;page 1 (800h-FFFh)
:
:
ORG 0x900
SUB1_P1:           ;called subroutine
:         ;page 1 (800h-FFFh)
:
RETURN          ;return to Call subroutine
:         ;in page 0 (000h-7FFh)

```

4.5 Indirect Addressing, INDF and FSR Registers

The INDF register is not a physical register. Addressing the INDF register will cause indirect addressing.

Indirect addressing is possible by using the INDF register. Any instruction using the INDF register actually accesses the register pointed to by the File Select Register, FSR. Reading the INDF register itself indirectly (FSR = '0') will read 00h. Writing to the INDF register indirectly results in a no-operation (although status bits may be affected). An effective 9-bit address is obtained by concatenating the 8-bit FSR register and the IRP bit (STATUS<7>), as shown in Figure 4-15. However, IRP is not used in the PIC16C71X devices.

A simple program to clear RAM locations 20h-2Fh using indirect addressing is shown in Example 4-2.

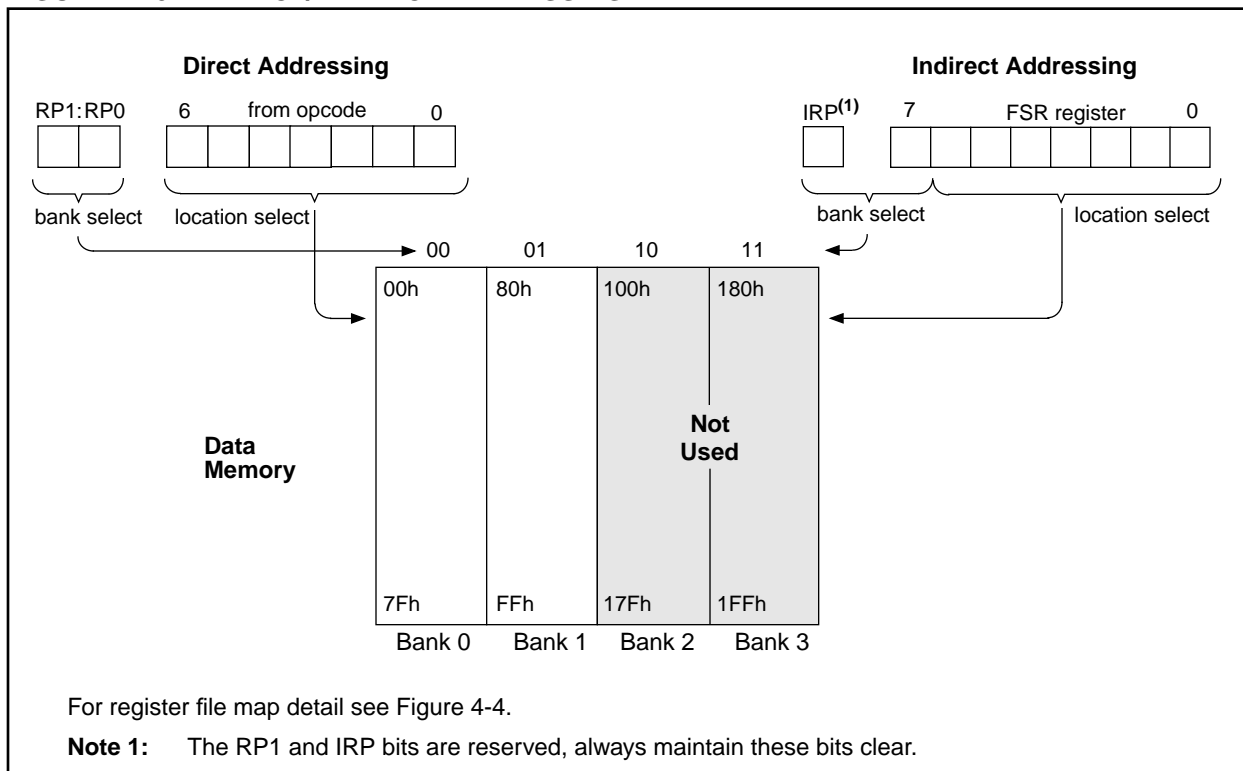
EXAMPLE 4-2: INDIRECT ADDRESSING

```

movlw  0x20    ;initialize pointer
movwf  FSR     ;to RAM
NEXT    clrf   INDF ;clear INDF register
        incf   FSR,F ;inc pointer
        btfss  FSR,4 ;all done?
        goto   NEXT ;no clear next
CONTINUE
:           ;yes continue

```

FIGURE 4-15: DIRECT/INDIRECT ADDRESSING



PIC16C71X

7.1 A/D Acquisition Requirements

For the A/D converter to meet its specified accuracy, the charge holding capacitor (CHOLD) must be allowed to fully charge to the input channel voltage level. The analog input model is shown in Figure 7-5. The source impedance (R_s) and the internal sampling switch (R_{ss}) impedance directly affect the time required to charge the capacitor CHOLD. The sampling switch (R_{ss}) impedance varies over the device voltage (V_{DD}), Figure 7-5. The source impedance affects the offset voltage at the analog input (due to pin leakage current).

The maximum recommended impedance for analog sources is 10 k Ω . After the analog input channel is selected (changed) this acquisition must be done before the conversion can be started.

To calculate the minimum acquisition time, Equation 7-1 may be used. This equation calculates the acquisition time to within 1/2 LSb error is used (512 steps for the A/D). The 1/2 LSb error is the maximum error allowed for the A/D to meet its specified accuracy.

EQUATION 7-1: A/D MINIMUM CHARGING TIME

$$V_{HOLD} = (V_{REF} - (V_{REF}/512)) \cdot (1 - e^{(-TCAP/CHOLD(RIC + R_{SS} + R_s))})$$

Given: $V_{HOLD} = (V_{REF}/512)$, for 1/2 LSb resolution

The above equation reduces to:

$$TCAP = -(51.2 \text{ pF})(1 \text{ k}\Omega + R_{SS} + R_s) \ln(1/511)$$

Example 7-1 shows the calculation of the minimum required acquisition time T_{ACQ} . This calculation is based on the following system assumptions.

CHOLD = 51.2 pF

$R_s = 10 \text{ k}\Omega$

1/2 LSb error

$V_{DD} = 5V \rightarrow R_{ss} = 7 \text{ k}\Omega$

Temp (application system max.) = 50°C

$V_{HOLD} = 0$ @ $t = 0$

Note 1: The reference voltage (V_{REF}) has no effect on the equation, since it cancels itself out.

Note 2: The charge holding capacitor (CHOLD) is not discharged after each conversion.

Note 3: The maximum recommended impedance for analog sources is 10 k Ω . This is required to meet the pin leakage specification.

Note 4: After a conversion has completed, a 2.0TAD delay must complete before acquisition can begin again. During this time the holding capacitor is not connected to the selected A/D input channel.

EXAMPLE 7-1: CALCULATING THE MINIMUM REQUIRED ACQUISITION TIME

$T_{ACQ} = \text{Amplifier Settling Time} +$

Holding Capacitor Charging Time +

Temperature Coefficient

$$T_{ACQ} = 5 \mu s + TCAP + [(Temp - 25^\circ C)(0.05 \mu s/^\circ C)]$$

$$TCAP = -CHOLD (RIC + R_{SS} + R_s) \ln(1/511)$$

$$-51.2 \text{ pF} (1 \text{ k}\Omega + 7 \text{ k}\Omega + 10 \text{ k}\Omega) \ln(0.0020)$$

$$-51.2 \text{ pF} (18 \text{ k}\Omega) \ln(0.0020)$$

$$-0.921 \mu s (-6.2364)$$

$$5.747 \mu s$$

$$T_{ACQ} = 5 \mu s + 5.747 \mu s + [(50^\circ C - 25^\circ C)(0.05 \mu s/^\circ C)]$$

$$10.747 \mu s + 1.25 \mu s$$

$$11.997 \mu s$$

FIGURE 7-5: ANALOG INPUT MODEL

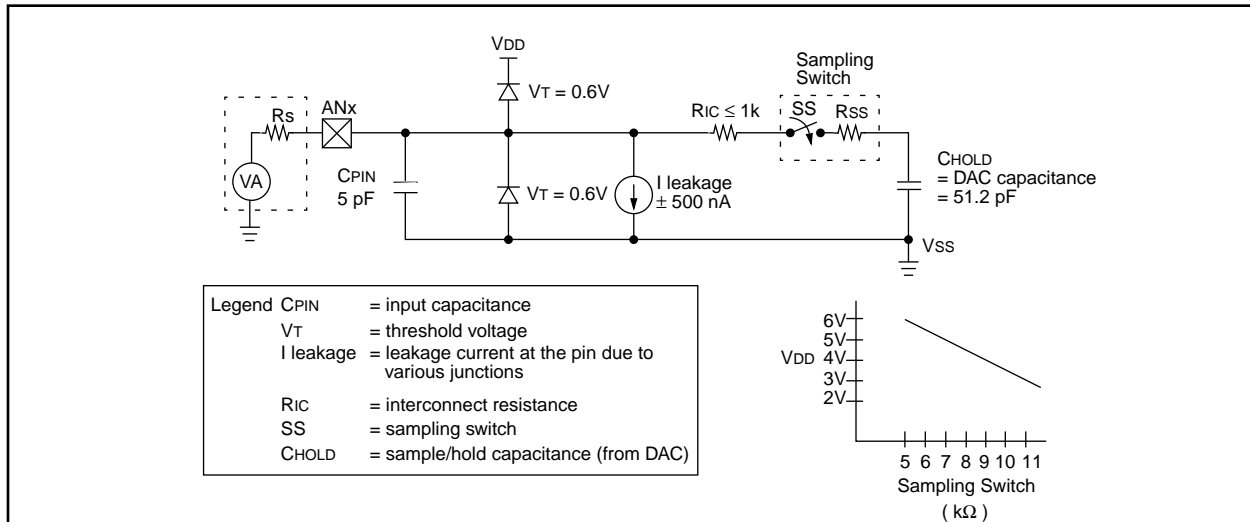


TABLE 8-12: INITIALIZATION CONDITIONS FOR ALL REGISTERS, PIC16C710/71/711

Register	Power-on Reset, Brown-out Reset ⁽⁵⁾	MCLR Resets WDT Reset	Wake-up via WDT or Interrupt
W	xxxx xxxx	uuuu uuuu	uuuu uuuu
INDF	N/A	N/A	N/A
TMR0	xxxx xxxx	uuuu uuuu	uuuu uuuu
PCL	0000h	0000h	PC + 1 ⁽²⁾
STATUS	0001 1xxx	000q quuu ⁽³⁾	uuuq quuu ⁽³⁾
FSR	xxxx xxxx	uuuu uuuu	uuuu uuuu
PORTA	---x 0000	---u 0000	---u uuuu
PORTB	xxxx xxxx	uuuu uuuu	uuuu uuuu
PCLATH	---0 0000	---0 0000	---u uuuu
INTCON	0000 000x	0000 000u	uuuu uuuu ⁽¹⁾
ADRES	xxxx xxxx	uuuu uuuu	uuuu uuuu
ADCON0	00-0 0000	00-0 0000	uu-u uuuu
OPTION	1111 1111	1111 1111	uuuu uuuu
TRISA	---1 1111	---1 1111	---u uuuu
TRISB	1111 1111	1111 1111	uuuu uuuu
PCON ⁽⁴⁾	---- --0u	---- --uu	---- --uu
ADCON1	---- --00	---- --00	---- --uu

Legend: u = unchanged, x = unknown, - = unimplemented bit, read as '0', q = value depends on condition

Note 1: One or more bits in INTCON will be affected (to cause wake-up).

2: When the wake-up is due to an interrupt and the GIE bit is set, the PC is loaded with the interrupt vector (0004h).

3: See Table 8-10 for reset value for specific condition.

4: The PCON register is not implemented on the PIC16C71.

5: Brown-out reset is not implemented on the PIC16C71.

PIC16C71X

FIGURE 8-17: INTERRUPT LOGIC, PIC16C710, 71, 711

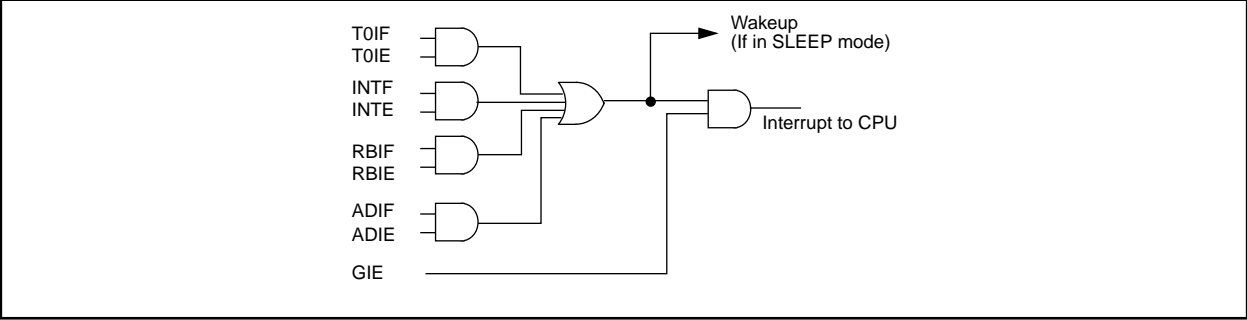
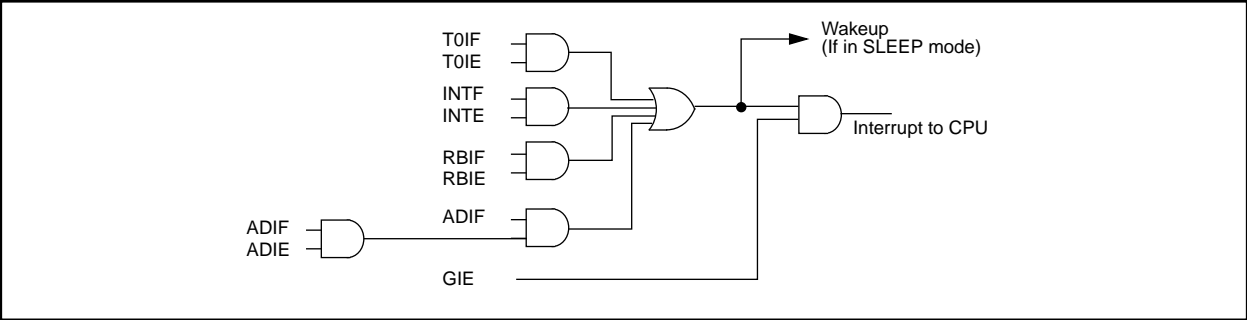


FIGURE 8-18: INTERRUPT LOGIC, PIC16C715



PIC16C71X

XORLW Exclusive OR Literal with W

Syntax: `[label] XORLW k`

Operands: $0 \leq k \leq 255$

Operation: $(W) .XOR. k \rightarrow (W)$

Status Affected: Z

Encoding:

11	1010	kkkk	kkkk
----	------	------	------

Description: The contents of the W register are XOR'ed with the eight bit literal 'k'. The result is placed in the W register.

Words: 1

Cycles: 1

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read literal 'k'	Process data	Write to W

Example: `XORLW 0xAF`
Before Instruction
W = 0xB5
After Instruction
W = 0x1A

XORWF Exclusive OR W with f

Syntax: `[label] XORWF f,d`

Operands: $0 \leq f \leq 127$
 $d \in [0,1]$

Operation: $(W) .XOR. (f) \rightarrow (dest)$

Status Affected: Z

Encoding:

00	0110	dfff	ffff
----	------	------	------

Description: Exclusive OR the contents of the W register with register 'f'. If 'd' is 0 the result is stored in the W register. If 'd' is 1 the result is stored back in register 'f'.

Words: 1

Cycles: 1

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read register 'f'	Process data	Write to dest

Example `XORWF REG 1`
Before Instruction
REG = 0xAF
W = 0xB5
After Instruction
REG = 0x1A
W = 0xB5

10.6 PICDEM-1 Low-Cost PIC16/17 Demonstration Board

The PICDEM-1 is a simple board which demonstrates the capabilities of several of Microchip's microcontrollers. The microcontrollers supported are: PIC16C5X (PIC16C54 to PIC16C58A), PIC16C61, PIC16C62X, PIC16C71, PIC16C8X, PIC17C42, PIC17C43 and PIC17C44. All necessary hardware and software is included to run basic demo programs. The users can program the sample microcontrollers provided with the PICDEM-1 board, on a PRO MATE II or PICSTART-Plus programmer, and easily test firmware. The user can also connect the PICDEM-1 board to the PICMASTER emulator and download the firmware to the emulator for testing. Additional prototype area is available for the user to build some additional hardware and connect it to the microcontroller socket(s). Some of the features include an RS-232 interface, a potentiometer for simulated analog input, push-button switches and eight LEDs connected to PORTB.

10.7 PICDEM-2 Low-Cost PIC16CXX Demonstration Board

The PICDEM-2 is a simple demonstration board that supports the PIC16C62, PIC16C64, PIC16C65, PIC16C73 and PIC16C74 microcontrollers. All the necessary hardware and software is included to run the basic demonstration programs. The user can program the sample microcontrollers provided with the PICDEM-2 board, on a PRO MATE II programmer or PICSTART-Plus, and easily test firmware. The PICMASTER emulator may also be used with the PICDEM-2 board to test firmware. Additional prototype area has been provided to the user for adding additional hardware and connecting it to the microcontroller socket(s). Some of the features include a RS-232 interface, push-button switches, a potentiometer for simulated analog input, a Serial EEPROM to demonstrate usage of the I²C bus and separate headers for connection to an LCD module and a keypad.

10.8 PICDEM-3 Low-Cost PIC16CXXX Demonstration Board

The PICDEM-3 is a simple demonstration board that supports the PIC16C923 and PIC16C924 in the PLCC package. It will also support future 44-pin PLCC microcontrollers with a LCD Module. All the necessary hardware and software is included to run the basic demonstration programs. The user can program the sample microcontrollers provided with the PICDEM-3 board, on a PRO MATE II programmer or PICSTART Plus with an adapter socket, and easily test firmware. The PICMASTER emulator may also be used with the PICDEM-3 board to test firmware. Additional prototype area has been provided to the user for adding hardware and connecting it to the microcontroller socket(s). Some of the features include

an RS-232 interface, push-button switches, a potentiometer for simulated analog input, a thermistor and separate headers for connection to an external LCD module and a keypad. Also provided on the PICDEM-3 board is an LCD panel, with 4 commons and 12 segments, that is capable of displaying time, temperature and day of the week. The PICDEM-3 provides an additional RS-232 interface and Windows 3.1 software for showing the demultiplexed LCD signals on a PC. A simple serial interface allows the user to construct a hardware demultiplexer for the LCD signals.

10.9 MPLAB Integrated Development Environment Software

The MPLAB IDE Software brings an ease of software development previously unseen in the 8-bit microcontroller market. MPLAB is a windows based application which contains:

- A full featured editor
- Three operating modes
 - editor
 - emulator
 - simulator
- A project manager
- Customizable tool bar and key mapping
- A status bar with project information
- Extensive on-line help

MPLAB allows you to:

- Edit your source files (either assembly or 'C')
- One touch assemble (or compile) and download to PIC16/17 tools (automatically updates all project information)
- Debug using:
 - source files
 - absolute listing file
- Transfer data dynamically via DDE (soon to be replaced by OLE)
- Run up to four emulators on the same PC

The ability to use MPLAB with Microchip's simulator allows a consistent platform and the ability to easily switch from the low cost simulator to the full featured emulator with minimal retraining due to development tools.

10.10 Assembler (MPASM)

The MPASM Universal Macro Assembler is a PC-hosted symbolic assembler. It supports all microcontroller series including the PIC12C5XX, PIC14000, PIC16C5X, PIC16CXXX, and PIC17CXX families.

MPASM offers full featured Macro capabilities, conditional assembly, and several source and listing formats. It generates various object code formats to support Microchip's development tools as well as third party programmers.

MPASM allows full symbolic debugging from PICMASTER, Microchip's Universal Emulator System.

11.5 Timing Diagrams and Specifications

FIGURE 11-2: EXTERNAL CLOCK TIMING

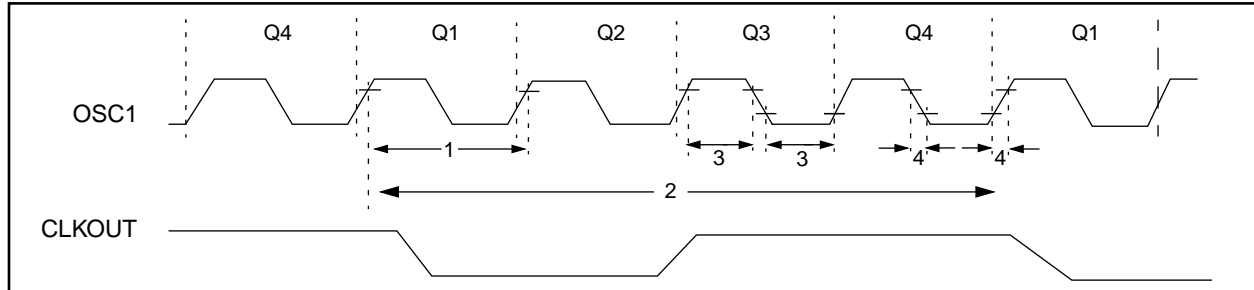


TABLE 11-2: EXTERNAL CLOCK TIMING REQUIREMENTS

Parameter No.	Sym	Characteristic	Min	Typ†	Max	Units	Conditions
1	Fosc	External CLKIN Frequency (Note 1)	DC	—	4	MHz	XT osc mode
			DC	—	4	MHz	HS osc mode (-04)
			DC	—	10	MHz	HS osc mode (-10)
			DC	—	20	MHz	HS osc mode (-20)
			DC	—	200	kHz	LP osc mode
	Tosc	Oscillator Frequency (Note 1)	DC	—	4	MHz	RC osc mode
			0.1	—	4	MHz	XT osc mode
			4	—	20	MHz	HS osc mode
			5	—	200	kHz	LP osc mode
	Tosc	External CLKIN Period (Note 1)	250	—	—	ns	XT osc mode
			250	—	—	ns	HS osc mode (-04)
			100	—	—	ns	HS osc mode (-10)
			50	—	—	ns	HS osc mode (-20)
			5	—	—	μs	LP osc mode
		Oscillator Period (Note 1)	250	—	—	ns	RC osc mode
			250	—	10,000	ns	XT osc mode
			250	—	250	ns	HS osc mode (-04)
2	Tcy	Instruction Cycle Time (Note 1)	200	—	DC	ns	Tcy = 4/Fosc
3	TosL, TosH	External Clock in (OSC1) High or Low Time	50	—	—	ns	XT oscillator
			2.5	—	—	μs	LP oscillator
			10	—	—	ns	HS oscillator
4	TosR, TosF	External Clock in (OSC1) Rise or Fall Time	—	—	25	ns	XT oscillator
			—	—	50	ns	LP oscillator
			—	—	15	ns	HS oscillator

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: Instruction cycle period (Tcy) equals four times the input oscillator time-base period. All specified values are based on characterization data for that particular oscillator type under standard operating conditions with the device executing code. Exceeding these specified limits may result in an unstable oscillator operation and/or higher than expected current consumption. All devices are tested to operate at "min." values with an external clock applied to the OSC1/CLKIN pin. When an external clock input is used, the "Max." cycle time limit is "DC" (no clock) for all devices. OSC2 is disconnected (has no loading) for the PIC16C710/711.

TABLE 11-6: A/D CONVERTER CHARACTERISTICS:
PIC16C710/711-04 (COMMERCIAL, INDUSTRIAL, EXTENDED)
PIC16C710/711-10 (COMMERCIAL, INDUSTRIAL, EXTENDED)
PIC16C710/711-20 (COMMERCIAL, INDUSTRIAL, EXTENDED)
PIC16LC710/711-04 (COMMERCIAL, INDUSTRIAL, EXTENDED)

Param No.	Sym	Characteristic	Min	Typ†	Max	Units	Conditions
A01	NR	Resolution	—	—	8-bits	bit	$V_{REF} = V_{DD}$, $V_{SS} \leq AIN \leq V_{REF}$
A02	EABS	Absolute error	—	—	$< \pm 1$	LSb	$V_{REF} = V_{DD}$, $V_{SS} \leq AIN \leq V_{REF}$
A03	EIL	Integral linearity error	—	—	$< \pm 1$	LSb	$V_{REF} = V_{DD}$, $V_{SS} \leq AIN \leq V_{REF}$
A04	EDL	Differential linearity error	—	—	$< \pm 1$	LSb	$V_{REF} = V_{DD}$, $V_{SS} \leq AIN \leq V_{REF}$
A05	EFS	Full scale error	—	—	$< \pm 1$	LSb	$V_{REF} = V_{DD}$, $V_{SS} \leq AIN \leq V_{REF}$
A06	EOFF	Offset error	—	—	$< \pm 1$	LSb	$V_{REF} = V_{DD}$, $V_{SS} \leq AIN \leq V_{REF}$
A10	—	Monotonicity	—	guaranteed	—	—	$V_{SS} \leq V_{AIN} \leq V_{REF}$
A20	VREF	Reference voltage	2.5V	—	$V_{DD} + 0.3$	V	
A25	VAIN	Analog input voltage	$V_{SS} - 0.3$	—	$V_{REF} + 0.3$	V	
A30	ZAIN	Recommended impedance of analog voltage source	—	—	10.0	k Ω	
A40	IAD	A/D conversion current (V_{DD})	—	180	—	μA	Average current consumption when A/D is on. (Note 1)
A50	IREF	VREF input current (Note 2)	10	—	1000	μA	During VAIN acquisition. Based on differential of V_{HOLD} to VAIN. To charge $CHOLD$ see Section 7.1. During A/D Conversion cycle
			—	—	10	μA	

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: When A/D is off, it will not consume any current other than minor leakage current.

The power-down current spec includes any such leakage from the A/D module.

2: VREF current is from RA3 pin or VDD pin, whichever is selected as reference input.

FIGURE 13-3: CLKOUT AND I/O TIMING

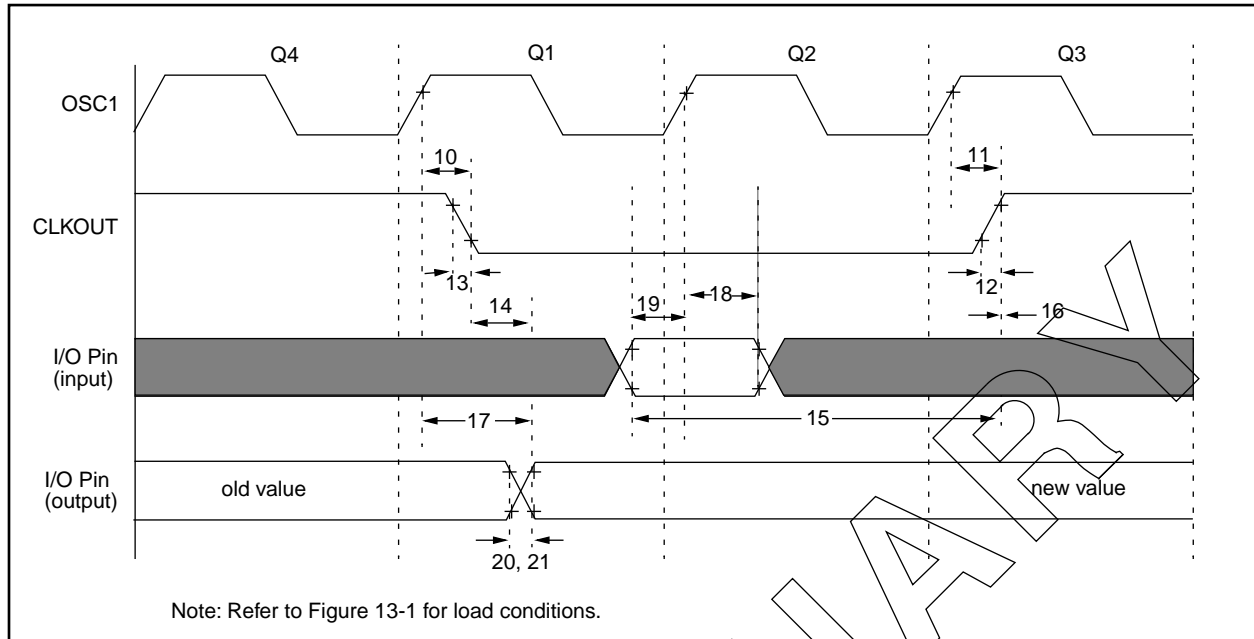


TABLE 13-3: CLKOUT AND I/O TIMING REQUIREMENTS

Parameter No.	Sym	Characteristic	Min	Typ†	Max	Units	Conditions
10*	TosH2ckL	OSC1↑ to CLKOUT↓	—	15	30	ns	Note 1
11*	TosH2ckH	OSC1↑ to CLKOUT↑	—	15	30	ns	Note 1
12*	TckR	CLKOUT rise time	—	5	15	ns	Note 1
13*	TckF	CLKOUT fall time	—	5	15	ns	Note 1
14*	TckL2ioV	CLKOUT ↓ to Port out valid	—	—	0.5T _{CY} + 20	ns	Note 1
15*	TioV2ckH	Port in valid before CLKOUT ↑	0.25T _{CY} + 25	—	—	ns	Note 1
16*	TckH2iol	Port in hold after CLKOUT ↑	0	—	—	ns	Note 1
17*	TosH2ioV	OSC1↑ (Q1 cycle) to Port out valid	—	—	80 - 100	ns	
18*	TosH2iol	OSC1↑ (Q2 cycle) to Port input invalid (I/O in hold time)	TBD	—	—	ns	
19*	TioV2osH	Port input valid to OSC1↑ (I/O in setup time)	TBD	—	—	ns	
20*	TioR	Port output rise time	—	10	25	ns	
			—	—	60	ns	
21*	TioF	Port output fall time	—	10	25	ns	
			—	—	60	ns	
22††*	Tinp	INT pin high or low time	20	—	—	ns	
23††*	Ttrp	RB7:RB4 change INT high or low time	20	—	—	ns	

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

†† These parameters are asynchronous events not related to any internal clock edges.

Note 1: Measurements are taken in RC Mode where CLKOUT output is 4 x T_{osc}.

PIC16C71X

Applicable Devices 710 71 711 715

FIGURE 13-7: A/D CONVERSION TIMING

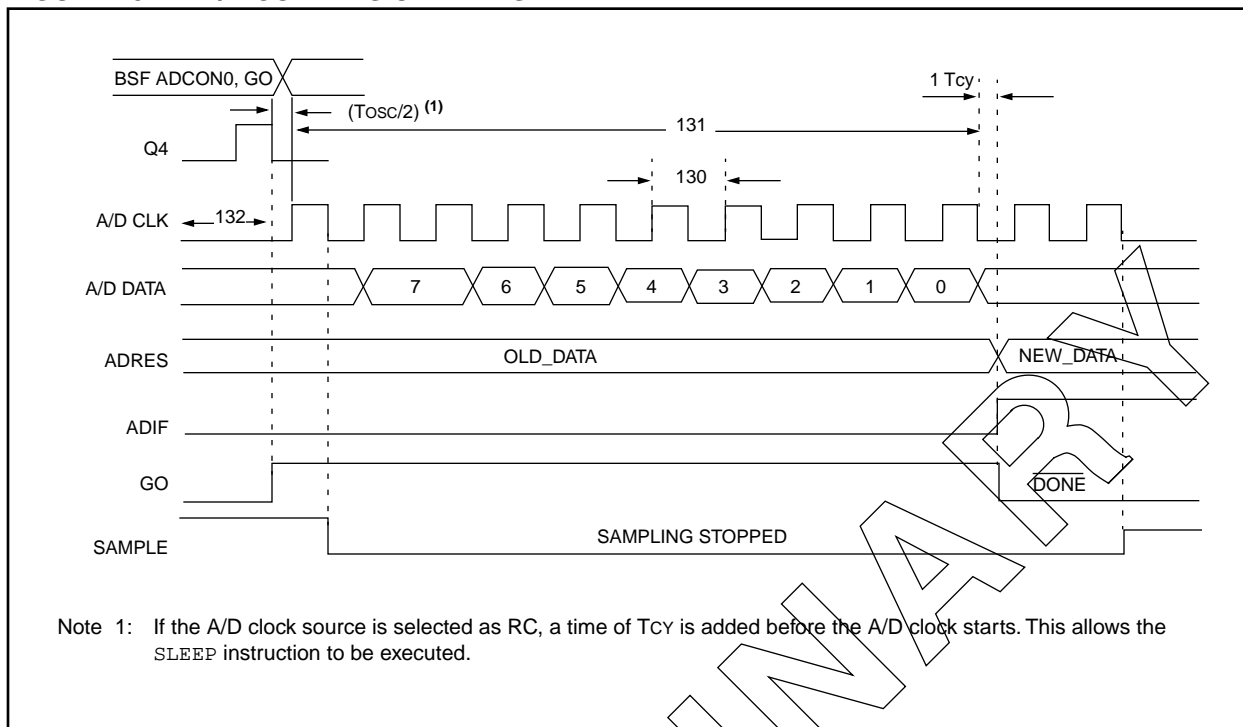


TABLE 13-8: A/D CONVERSION REQUIREMENTS

Parameter No.	Sym	Characteristic	Min	Typ†	Max	Units	Conditions
130	TAD	A/D clock period	1.6	—	—	μs	VREF ≥ 3.0V
130	TAD	A/D Internal RC Oscillator source	2.0	—	—	μs	VREF full range
			3.0	6.0	9.0	μs	ADCS1:ADCS0 = 11 (RC oscillator source)
			2.0	4.0	6.0	μs	PIC16LC715, VDD = 3.0V
							PIC16C715
131	TCNV	Conversion time (not including S/H time). Note 1	—	9.5TAD	—	—	
132	TACQ	Acquisition time	Note 2	20	—	μs	

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: ADRES register may be read on the following T_{CY} cycle.

14.0 DC AND AC CHARACTERISTICS GRAPHS AND TABLES FOR PIC16C715

The graphs and tables provided in this section are for design guidance and are not tested or guaranteed.

In some graphs or tables the data presented are outside specified operating range (i.e., outside specified V_{DD} range). This is for information only and devices are guaranteed to operate properly only within the specified range.

Note: The data presented in this section is a statistical summary of data collected on units from different lots over a period of time and matrix samples. 'Typical' represents the mean of the distribution at 25°C, while 'max' or 'min' represents (mean +3 σ) and (mean -3 σ) respectively where σ is standard deviation.

FIGURE 14-1: TYPICAL I_{PD} vs. V_{DD} (WDT DISABLED, RC MODE)

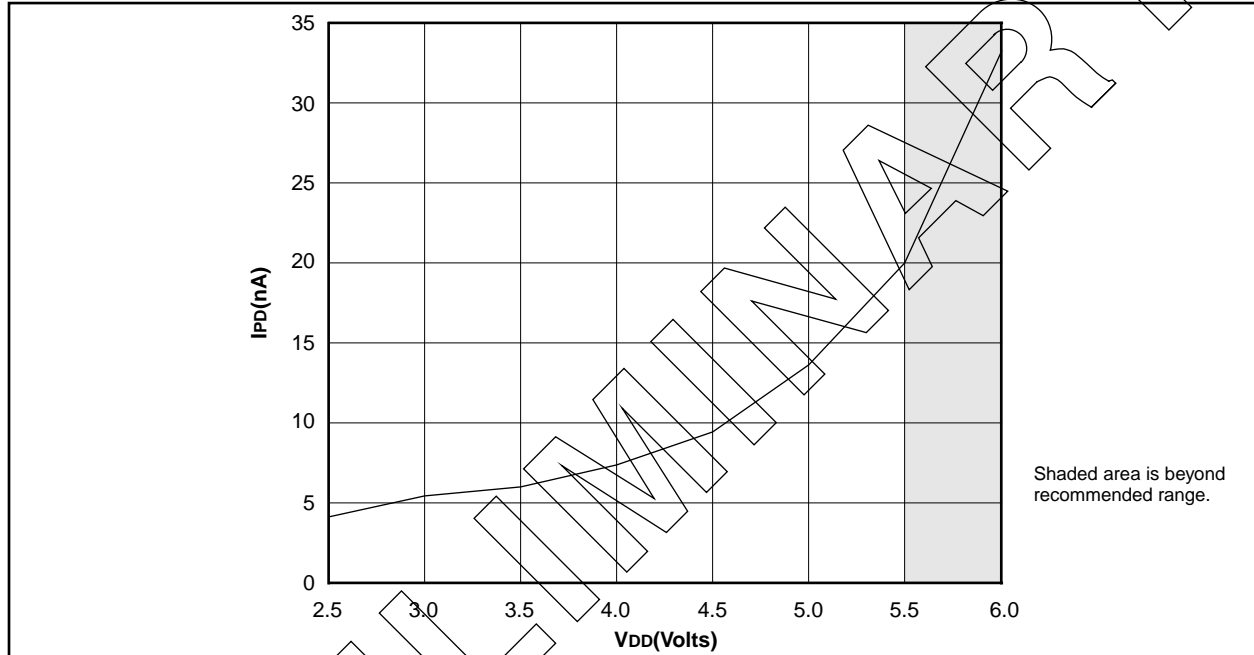


FIGURE 14-2: MAXIMUM I_{PD} vs. V_{DD} (WDT DISABLED, RC MODE)

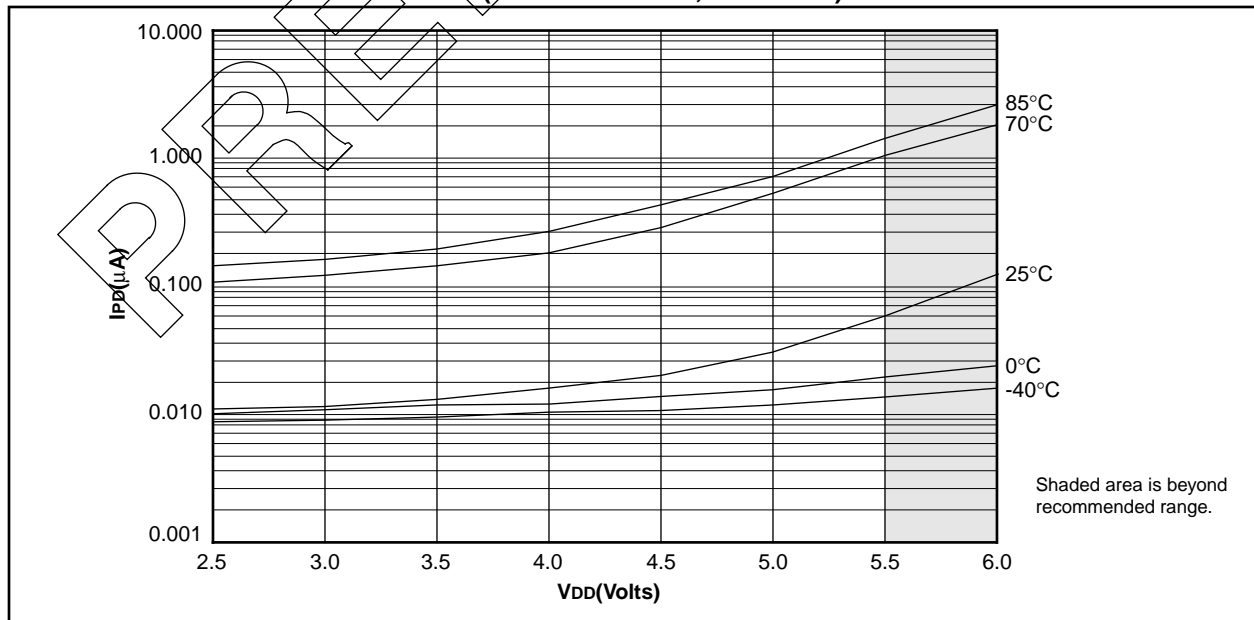


FIGURE 14-14: TYPICAL I_{DD} vs. FREQUENCY (RC MODE @ 100 pF, 25°C)

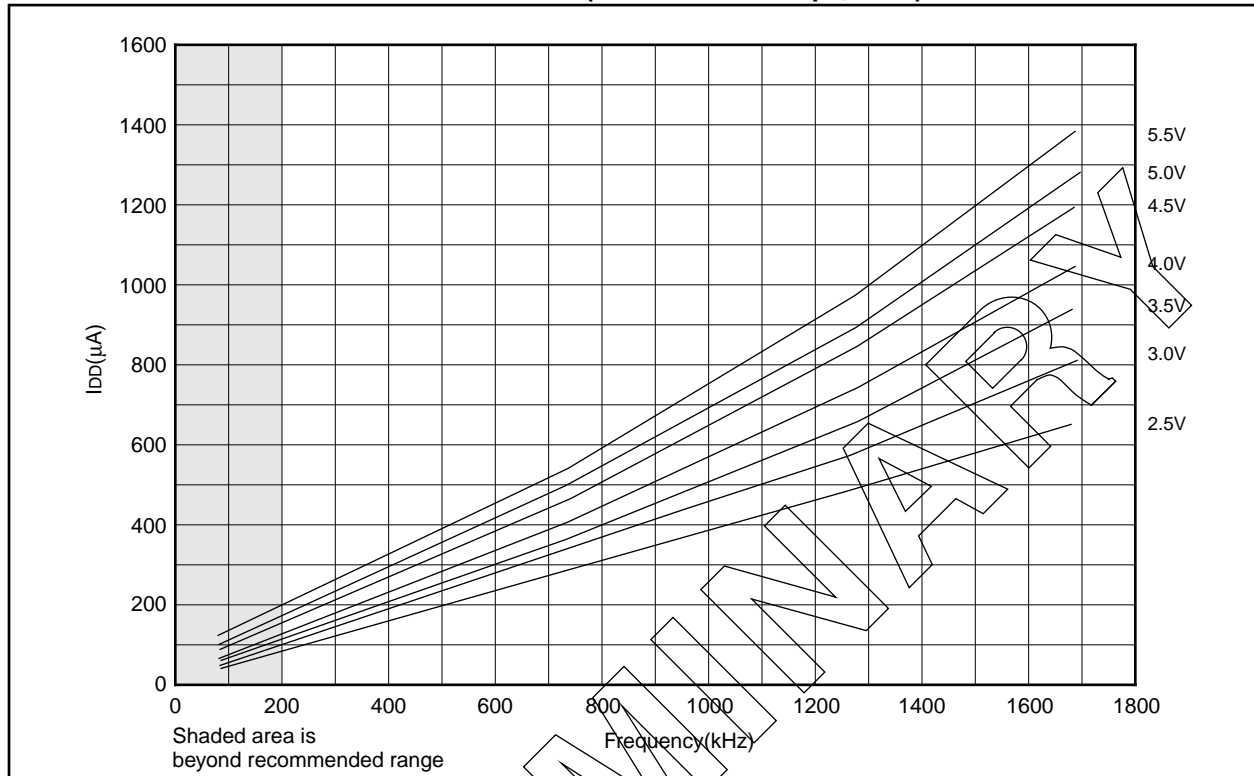
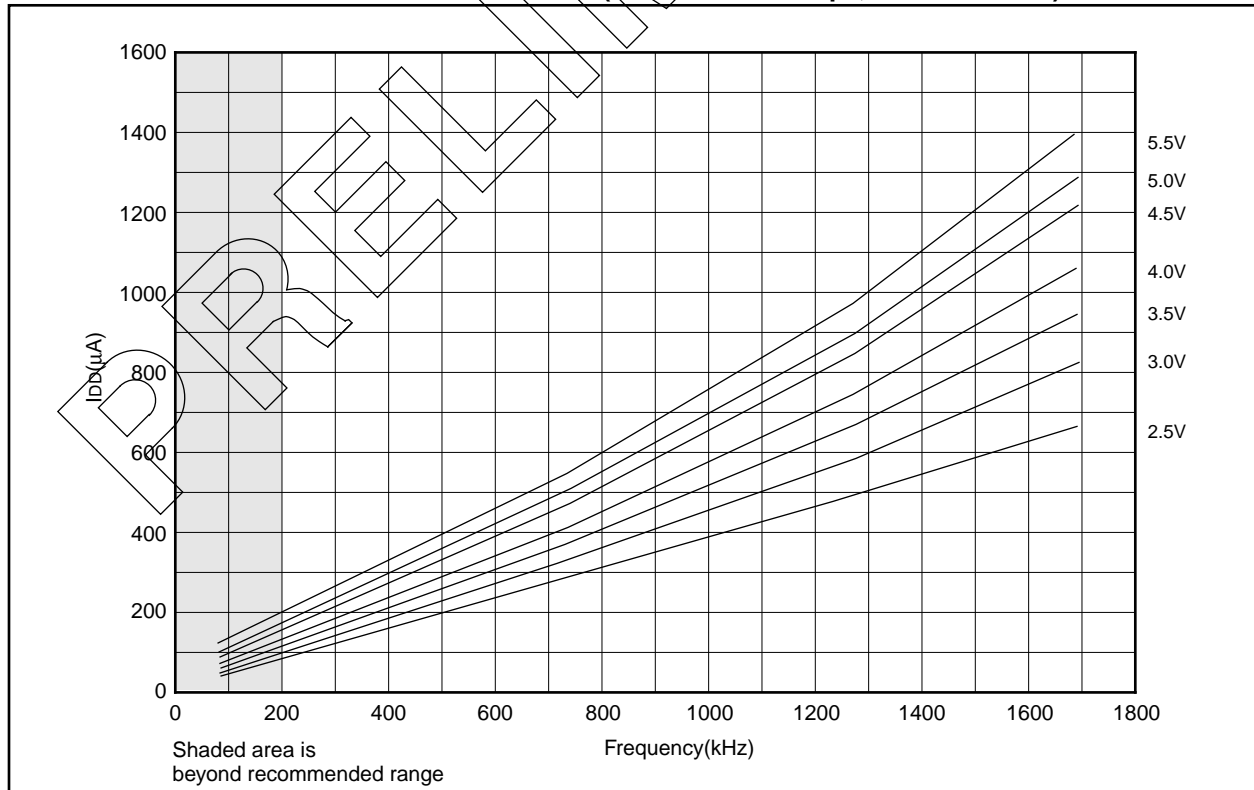


FIGURE 14-15: MAXIMUM I_{DD} vs. FREQUENCY (RC MODE @ 100 pF, -40°C TO 85°C)



PIC16C71X

Applicable Devices

710	71	711	715
-----	----	-----	-----

FIGURE 14-16: TYPICAL I_{DD} vs. FREQUENCY (RC MODE @ 300 pF, 25°C)

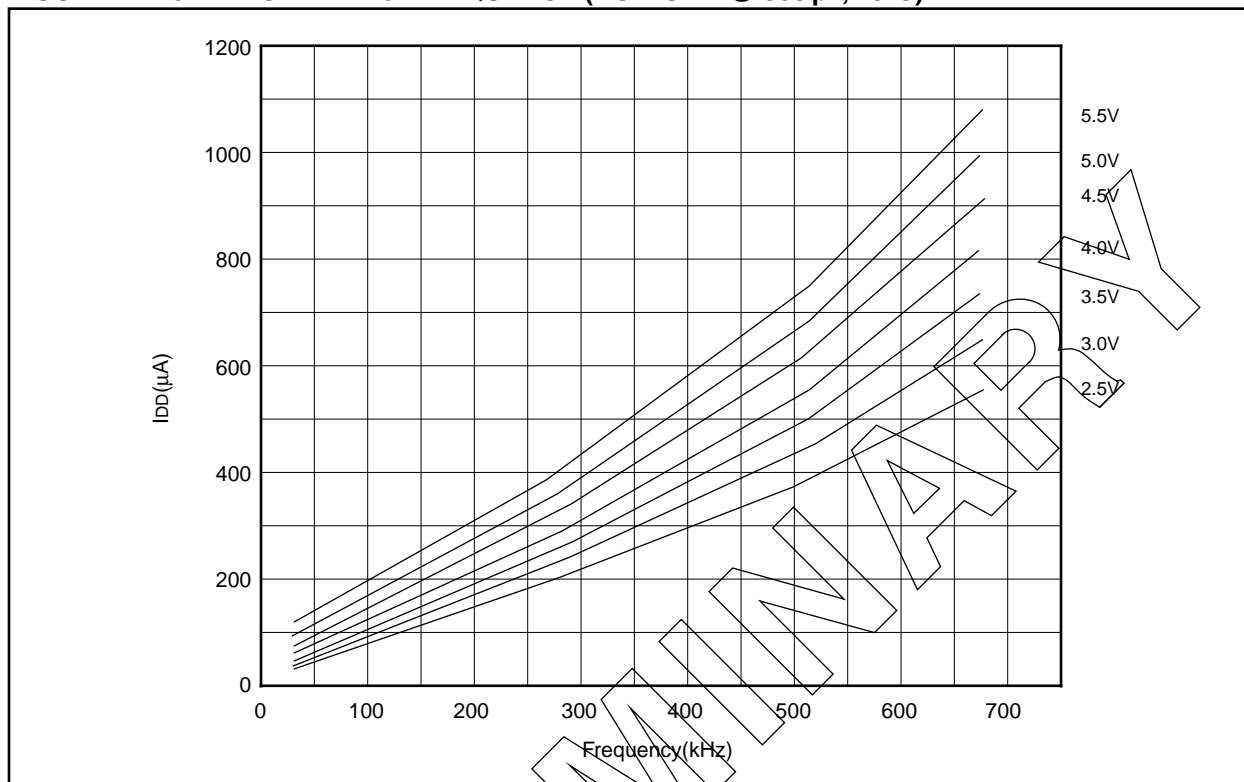
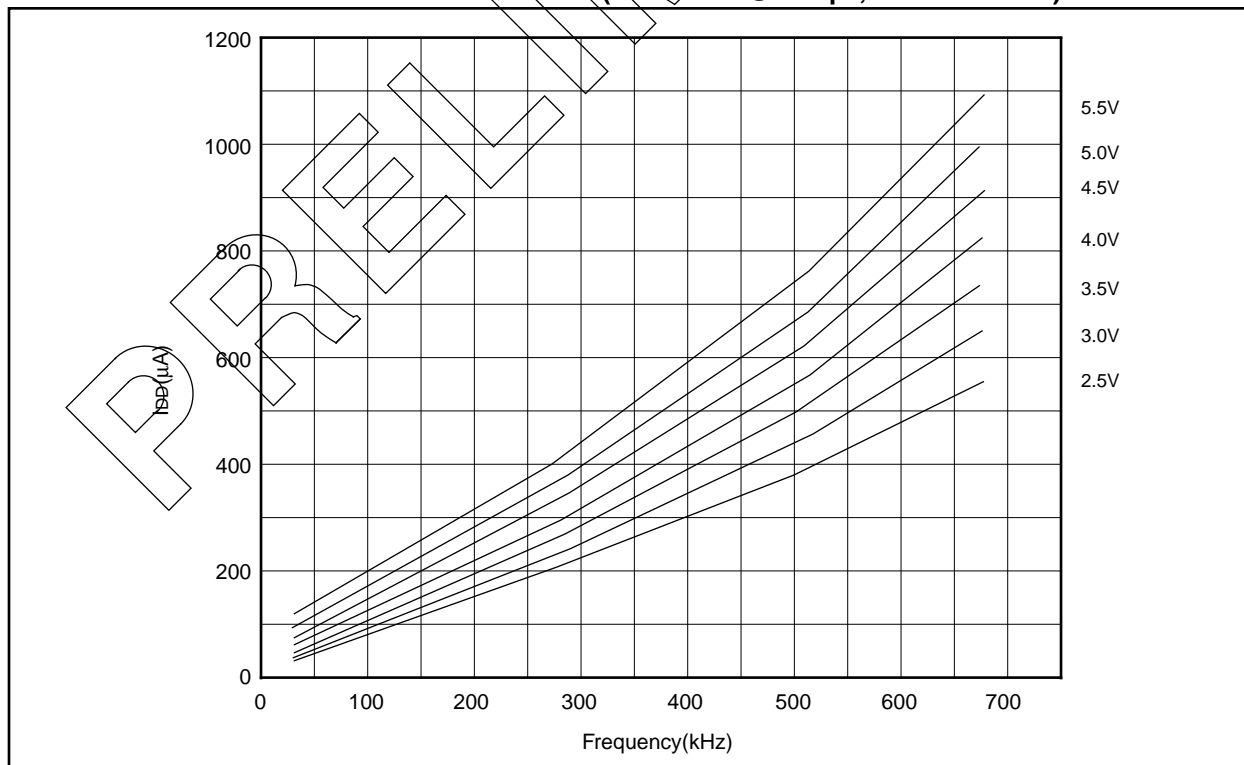


FIGURE 14-17: MAXIMUM I_{DD} vs. FREQUENCY (RC MODE @ 300 pF, -40°C TO 85°C)



15.5 Timing Diagrams and Specifications

FIGURE 15-2: EXTERNAL CLOCK TIMING

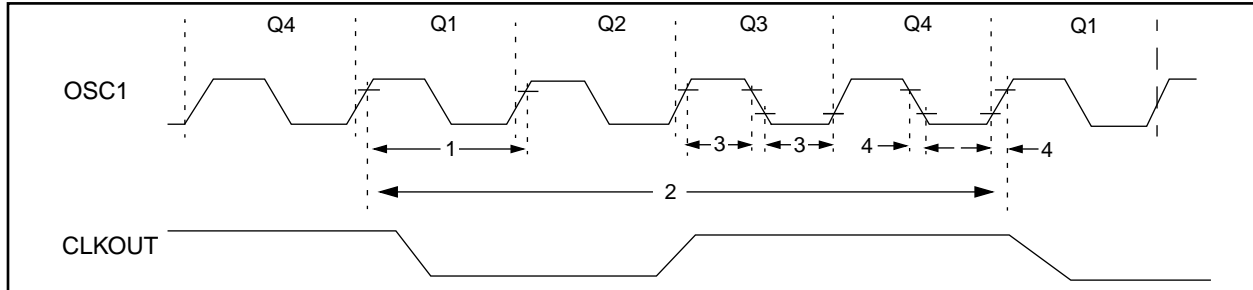


TABLE 15-2: EXTERNAL CLOCK TIMING REQUIREMENTS

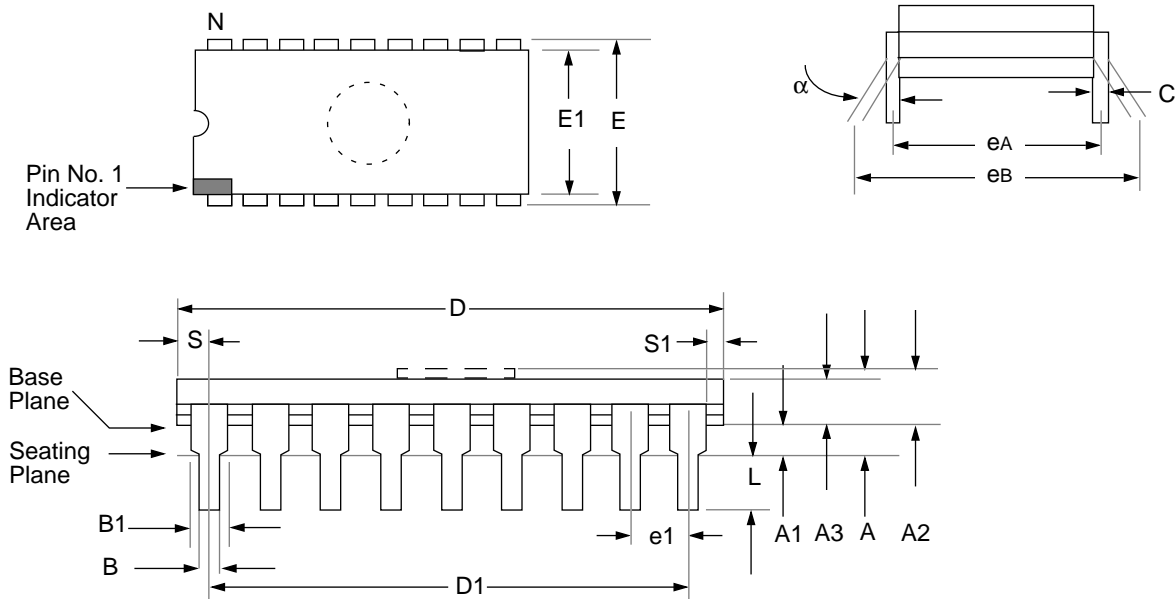
Parameter No.	Sym	Characteristic	Min	Typ†	Max	Units	Conditions
	Fosc	External CLKIN Frequency (Note 1)	DC	—	4	MHz	XT osc mode
			DC	—	4	MHz	HS osc mode (-04)
			DC	—	20	MHz	HS osc mode (-20)
			DC	—	200	kHz	LP osc mode
		Oscillator Frequency (Note 1)	DC	—	4	MHz	RC osc mode
			0.1	—	4	MHz	XT osc mode
			1	—	4	MHz	HS osc mode
			1	—	20	MHz	HS osc mode
1	Tosc	External CLKIN Period (Note 1)	250	—	—	ns	XT osc mode
			250	—	—	ns	HS osc mode (-04)
			50	—	—	ns	HS osc mode (-20)
			5	—	—	μs	LP osc mode
		Oscillator Period (Note 1)	250	—	—	ns	RC osc mode
			250	—	10,000	ns	XT osc mode
			250	—	1,000	ns	HS osc mode (-04)
			50	—	1,000	ns	HS osc mode (-20)
2	TCY	Instruction Cycle Time (Note 1)	1.0	TCY	DC	μs	TCY = 4/Fosc
			15	—	—	ns	HS oscillator
3	TosL, TosH	External Clock in (OSC1) High or Low Time	50	—	—	ns	XT oscillator
			2.5	—	—	μs	LP oscillator
			10	—	—	ns	HS oscillator
4	TosR, TosF	External Clock in (OSC1) Rise or Fall Time	25	—	—	ns	XT oscillator
			50	—	—	ns	LP oscillator
			15	—	—	ns	HS oscillator

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: Instruction cycle period (TCY) equals four times the input oscillator time-base period. All specified values are based on characterization data for that particular oscillator type under standard operating conditions with the device executing code. Exceeding these specified limits may result in an unstable oscillator operation and/or higher than expected current consumption. All devices are tested to operate at "min." values with an external clock applied to the OSC1/CLKIN pin. When an external clock input is used, the "Max." cycle time limit is "DC" (no clock) for all devices. OSC2 is disconnected (has no loading) for the PIC16C71.

17.0 PACKAGING INFORMATION

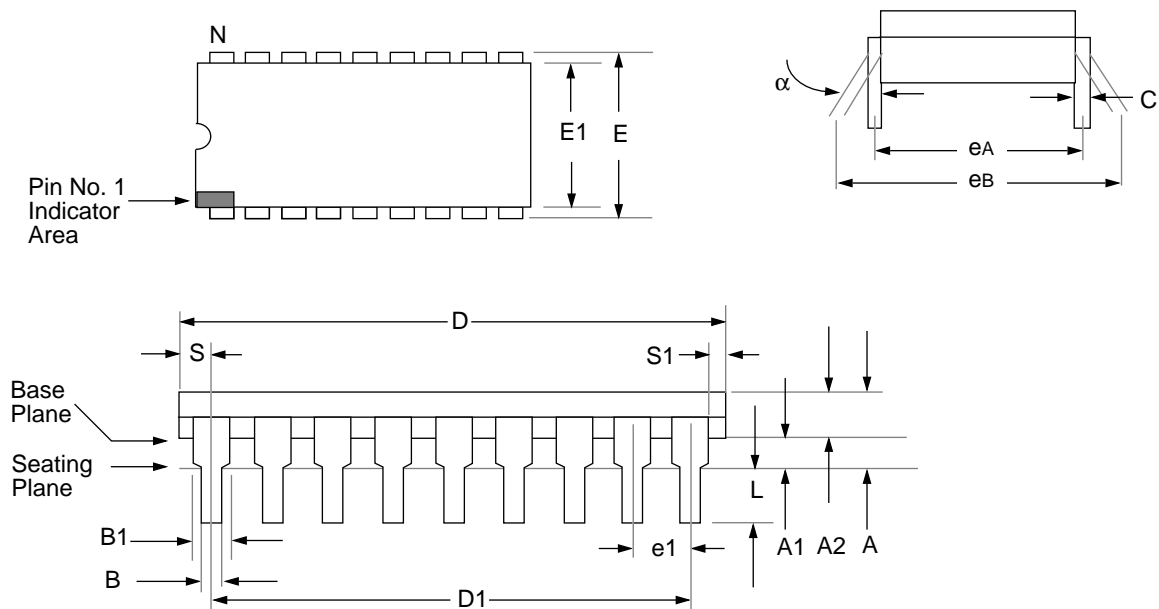
17.1 18-Lead Ceramic Cerdip Dual In-line with Window (300 mil) (JW)



Package Group: Ceramic Cerdip Dual In-Line (CDP)						
Symbol	Millimeters			Inches		
	Min	Max	Notes	Min	Max	Notes
α	0°	10°		0°	10°	
A	—	5.080		—	0.200	
A1	0.381	1.7780		0.015	0.070	
A2	3.810	4.699		0.150	0.185	
A3	3.810	4.445		0.150	0.175	
B	0.355	0.585		0.014	0.023	
B1	1.270	1.651	Typical	0.050	0.065	Typical
C	0.203	0.381	Typical	0.008	0.015	Typical
D	22.352	23.622		0.880	0.930	
D1	20.320	20.320	Reference	0.800	0.800	Reference
E	7.620	8.382		0.300	0.330	
E1	5.588	7.874		0.220	0.310	
e1	2.540	2.540	Reference	0.100	0.100	Reference
eA	7.366	8.128	Typical	0.290	0.320	Typical
eB	7.620	10.160		0.300	0.400	
L	3.175	3.810		0.125	0.150	
N	18	18		18	18	
S	0.508	1.397		0.020	0.055	
S1	0.381	1.270		0.015	0.050	

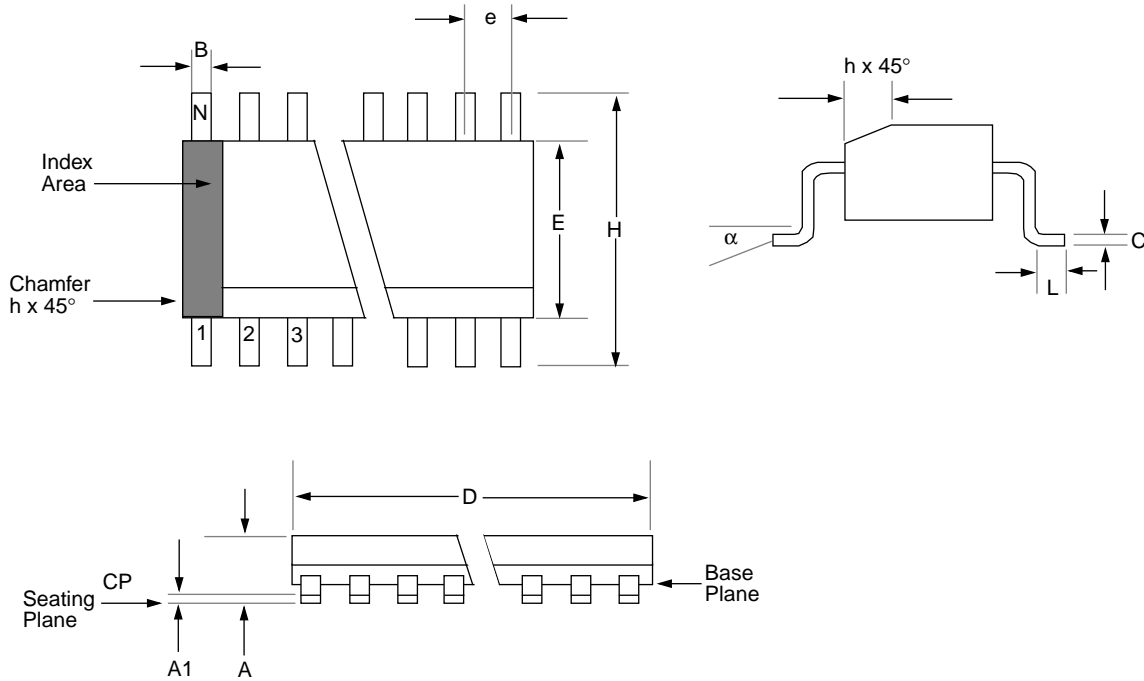
PIC16C71X

17.2 18-Lead Plastic Dual In-line (300 mil) (P)



Package Group: Plastic Dual In-Line (PLA)						
Symbol	Millimeters			Inches		
	Min	Max	Notes	Min	Max	Notes
α	0°	10°		0°	10°	
A	—	4.064		—	0.160	
A1	0.381	—		0.015	—	
A2	3.048	3.810		0.120	0.150	
B	0.355	0.559		0.014	0.022	
B1	1.524	1.524	Reference	0.060	0.060	Reference
C	0.203	0.381	Typical	0.008	0.015	Typical
D	22.479	23.495		0.885	0.925	
D1	20.320	20.320	Reference	0.800	0.800	Reference
E	7.620	8.255		0.300	0.325	
E1	6.096	7.112		0.240	0.280	
e1	2.489	2.591	Typical	0.098	0.102	Typical
eA	7.620	7.620	Reference	0.300	0.300	Reference
eB	7.874	9.906		0.310	0.390	
L	3.048	3.556		0.120	0.140	
N	18	18		18	18	
S	0.889	—		0.035	—	
S1	0.127	—		0.005	—	

17.3 18-Lead Plastic Surface Mount (SOIC - Wide, 300 mil Body)(SO)



Package Group: Plastic SOIC (SO)						
Symbol	Millimeters			Inches		
	Min	Max	Notes	Min	Max	Notes
α	0°	8°		0°	8°	
A	2.362	2.642		0.093	0.104	
A1	0.101	0.300		0.004	0.012	
B	0.355	0.483		0.014	0.019	
C	0.241	0.318		0.009	0.013	
D	11.353	11.735		0.447	0.462	
E	7.416	7.595		0.292	0.299	
e	1.270	1.270	Reference	0.050	0.050	Reference
H	10.007	10.643		0.394	0.419	
h	0.381	0.762		0.015	0.030	
L	0.406	1.143		0.016	0.045	
N	18	18		18	18	
CP	—	0.102		—	0.004	

PIC16C71X

I

I/O Ports	
PORTA	25
PORTB	27
Section	25
I/O Programming Considerations	30
ICEPIC Low-Cost PIC16CXXX In-Circuit Emulator	85
In-Circuit Serial Programming	47, 67
INDF Register	14, 16, 24
Indirect Addressing	24
Instruction Cycle	10
Instruction Flow/Pipelining	10
Instruction Format	69
Instruction Set	
ADDLW	71
ADDWF	71
ANDLW	71
ANDWF	71
BCF	72
BSF	72
BTFSC	72
BTFSS	73
CALL	73
CLRF	74
CLRW	74
CLRWD	74
COMF	75
DECF	75
DECFSZ	75
GOTO	76
INCF	76
INCFSZ	77
IORLW	77
IORWF	78
MOVF	78
MOVLW	78
MOVWF	78
NOP	79
OPTION	79
RETFIE	79
RETLW	80
RETURN	80
RLF	81
RRF	81
SLEEP	82
SUBLW	82
SUBWF	83
SWAPF	83
TRIS	83
XORLW	84
XORWF	84
Section	69
Summary Table	70
INT Interrupt	63
INTCON Register	19
INTE bit	19
INTEDG bit	18, 63
Internal Sampling Switch (Rss) Impedance	40
Interrupts	47
A/D	61
External	61
PORTB Change	61
PortB Change	63
RB7:RB4 Port Change	27
Section	61
TMR0	63

TMR0 Overflow	61
INTF bit	19
IRP bit	17

K

KeeLoq® Evaluation and Programming Tools	87
--	----

L

Loading of PC	23
LP	54

M

MCLR	52, 56
Memory	
Data Memory	12
Program Memory	11
Register File Maps	
PIC16C71	12
PIC16C710	12
PIC16C711	13
PIC16C715	13
MP-DriveWay™ - Application Code Generator	87
MPEEN bit	22, 48
MPLAB™ C	87
MPLAB™ Integrated Development Environment	
Software	86

O

OPCODE	69
OPTION Register	18
Orthogonal	7
OSC selection	47
Oscillator	
HS	49, 54
LP	49, 54
RC	49
XT	49, 54
Oscillator Configurations	49
Oscillator Start-up Timer (OST)	53

P

Packaging	
18-Lead Cerdip w/Window	155
18-Lead PDIP	156
18-Lead SOIC	157
20-Lead SSOP	158
Paging, Program Memory	23
PCL Register	14, 15, 16, 23
PCLATH	57, 58
PCLATH Register	14, 15, 16, 23
PCON Register	22, 54
PD bit	17, 52, 55
PER bit	22
PIC16C71	147
AC Characteristics	147
PICDEM-1 Low-Cost PIC16/17 Demo Board	86
PICDEM-2 Low-Cost PIC16CXX Demo Board	86
PICDEM-3 Low-Cost PIC16CXXX Demo Board	86
PICMASTER® In-Circuit Emulator	85
PICSTART® Plus Entry Level Development System	85
PIE1 Register	20
Pin Functions	
MCLR/VPP	9
OSC1/CLKIN	9
OSC2/CLKOUT	9
RA0/AN0	9
RA1/AN1	9